PIN A1

REFERENCE

NDTE 3



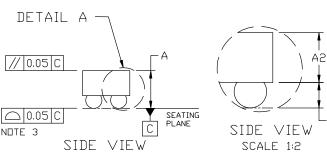


## WLCSP4 0.76x0.76x0.605 CASE 567FJ **ISSUE C**

**DATE 27 MAR 2023** 

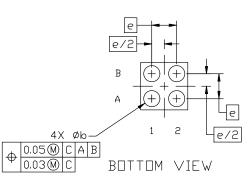
## NOTES:

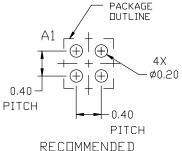
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.



DIM	MILLIMETERS			
	MIN.	N□M.	MAX.	
Α	0.555	0.605	0.655	
A1	0.180	0.205	0.230	
A2	0.375	0.400	0.425	
b	0.236	0.261	0.286	
D	0.73	0.76	0.79	
Е	0.73	0.76	0.79	
е	0.40 BSC			

.... . ....





## MOUNTING FOOTPRINT\*

For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **GENERIC MARKING DIAGRAM\***

TOP VIEW



XXX = Specific Device Code

= Assembly Location Α Υ = Year W = Work Week = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	WLCSP4 0.76x0.76x0.605	•	PAGE 1 OF 1	

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